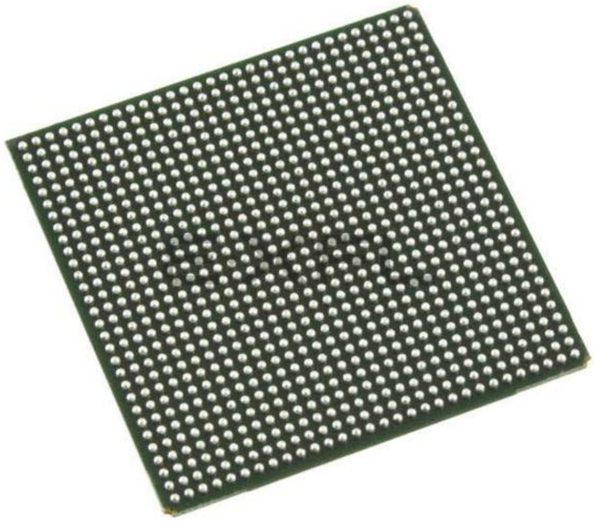


Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	8375
Number of Logic Elements/Cells	67000
Total RAM Bits	4642816
Number of I/O	416
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m70se-7fn900c

Delay Locked Loops (DLL)

In addition to PLLs, the LatticeECP2/M family of devices has two DLLs per device.

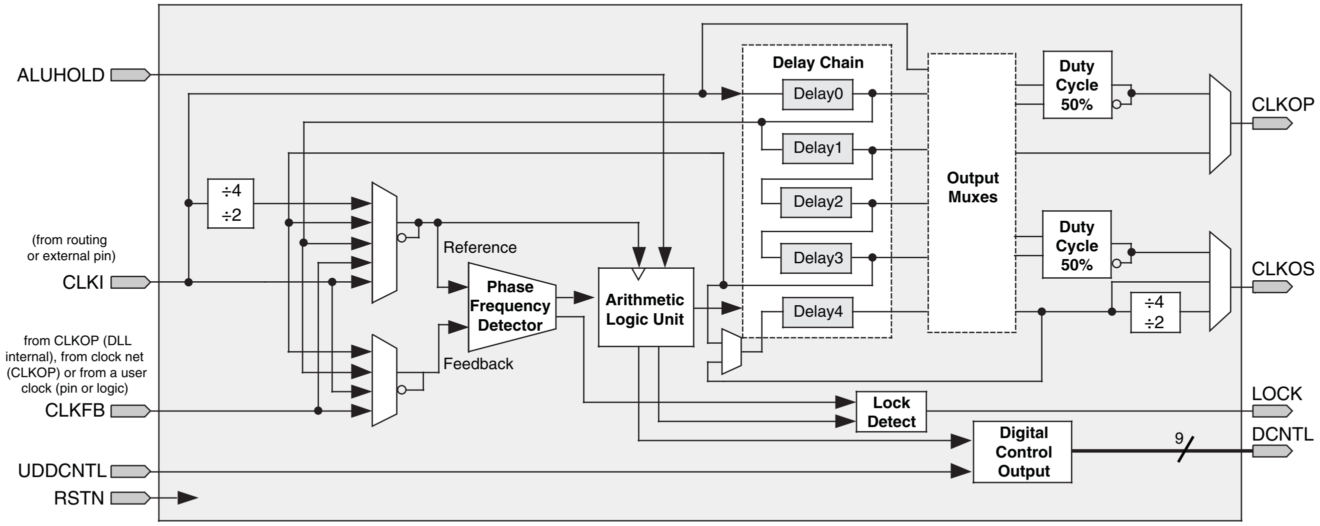
CLKI is the input frequency (generated either from the pin or routing) for the DLL. CLKI feeds into the output muxes block to bypass the DLL, directly to the DELAY CHAIN block and (directly or through divider circuit) to the reference input of the Phase Frequency Detector (PFD) input mux. The reference signal for the PFD can also be generated from the Delay Chain and CLKFB signals. The feedback input to the PFD is generated from the CLKFB pin, CLKI or from tapped signal from the Delay chain.

The PFD produces a binary number proportional to the phase and frequency difference between the reference and feedback signals. This binary output of the PFD is fed into a Arithmetic Logic Unit (ALU). Based on these inputs, the ALU determines the correct digital control codes to send to the delay chain in order to better match the reference and feedback signals. This digital code from the ALU is also transmitted via the Digital Control bus (DCNTL) bus to its associated DLLDELA delay block. The ALUHOLD input allows the user to suspend the ALU output at its current value. The UDDCNTL signal allows the user to latch the current value on the DCNTL bus.

The DLL has two independent clock outputs, CLKOP and CLKOS. These outputs can individually select one of the outputs from the tapped delay line. The CLKOS has optional fine phase shift and divider blocks to allow this output to be further modified, if required. The fine phase shift block allows the CLKOS output to phase shifted a further 45, 22.5 or 11.25 degrees relative to its normal position. Both the CLKOS and CLKOP outputs are available with optional duty cycle correction. Divide by two and divide by four frequencies are available at CLKOS. The LOCK output signal is asserted when the DLL is locked. Figure 2-6 shows the DLL block diagram and Table 2-5 provides a description of the DLL inputs and outputs.

The user can configure the DLL for many common functions such as time reference delay mode and clock injection removal mode. Lattice provides primitives in its design tools for these functions. For more information about the DLL, please see the list of additional technical documentation at the end of this data sheet.

Figure 2-6. Delay Locked Loop Diagram (DLL)



sysMEM Memory

LatticeECP2/M devices contains a number of sysMEM Embedded Block RAM (EBR). The EBR consists of an 18-Kbit RAM with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6. FIFOs can be implemented in sysMEM EBR blocks by implementing support logic with PFUs. The EBR block facilitates parity checking by supporting an optional parity bit for each data byte. EBR blocks provide byte-enable support for configurations with18-bit and 36-bit data widths.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
True Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18
Pseudo Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1, and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Memory Cascading

Larger and deeper blocks of RAM can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output.

EBR memory supports two forms of write behavior for single port or dual port operation:

1. Normal – Data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

Register-to-Register Performance (Continued)

Function	-7 Timing	Units
36x36 Multiplier (All Registers)	372	MHz
18x18 Multiplier/Accumulate (Input and Output Registers)	295	MHz
18x18 Multiplier-Add/Sub-Sum (All Registers)	420	MHz
DSP IP Functions		
16-Tap Fully-Parallel FIR Filter	304	MHz
1024-pt, Radix 4, Decimation in Frequency FFT	227	MHz
8x8 Matrix Multiplier	223	MHz

Derating Timing Tables

Logic timing provided in the following sections of this data sheet and the Diamond design tool are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best case process, can be much better than the values given in the tables. The Diamond design tool can provide logic timing numbers at a particular temperature and voltage.

LatticeECP2/M External Switching Characteristics[9]

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (using Primary Clock without PLL)[1]									
t_{CO}	Clock to Output - PIO Output Register	LFE2-6	—	3.50	—	3.90	—	4.20	ns
		LFE2-12	—	3.50	—	3.90	—	4.20	ns
		LFE2-20	—	3.50	—	3.90	—	4.20	ns
		LFE2-35	—	3.50	—	3.90	—	4.20	ns
		LFE2-50	—	3.50	—	3.90	—	4.20	ns
		LFE2-70	—	3.70	—	4.10	—	4.40	ns
		LFE2M20	—	3.90	—	4.30	—	4.70	ns
		LFE2M35	—	3.90	—	4.30	—	4.70	ns
		LFE2M50	—	4.50	—	5.00	—	5.40	ns
		LFE2M70	—	4.50	—	5.00	—	5.40	ns
		LFE2M100	—	4.50	—	5.00	—	5.40	ns
t_{SU}	Clock to Data Setup - PIO Input Register	LFE2-6	0.00	—	0.00	—	0.00	—	ns
		LFE2-12	0.00	—	0.00	—	0.00	—	ns
		LFE2-20	0.00	—	0.00	—	0.00	—	ns
		LFE2-35	0.00	—	0.00	—	0.00	—	ns
		LFE2-50	0.00	—	0.00	—	0.00	—	ns
		LFE2-70	0.00	—	0.00	—	0.00	—	ns
		LFE2M20	0.00	—	0.00	—	0.00	—	ns
		LFE2M35	0.00	—	0.00	—	0.00	—	ns
		LFE2M50	0.00	—	0.00	—	0.00	—	ns
		LFE2M70	0.00	—	0.00	—	0.00	—	ns
		LFE2M100	0.00	—	0.00	—	0.00	—	ns
t_H	Clock to Data Hold - PIO Input Register	LFE2-6	1.40	—	1.70	—	1.90	—	ns
		LFE2-12	1.40	—	1.70	—	1.90	—	ns
		LFE2-20	1.40	—	1.70	—	1.90	—	ns
		LFE2-35	1.40	—	1.70	—	1.90	—	ns
		LFE2-50	1.40	—	1.70	—	1.90	—	ns
		LFE2-70	1.40	—	1.70	—	1.90	—	ns
		LFE2M20	1.40	—	1.70	—	1.90	—	ns
		LFE2M35	1.40	—	1.70	—	1.90	—	ns
		LFE2M50	1.80	—	2.10	—	2.30	—	ns
		LFE2M70	1.80	—	2.10	—	2.30	—	ns
		LFE2M100	1.80	—	2.10	—	2.30	—	ns

LatticeECP2/M External Switching Characteristics[9] (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{H_DELE}	Clock to Data Hold - PIO Input Register with Input Data Delay	LFE2-6	0.00	—	0.00	—	0.00	—	ns
		LFE2-12	0.00	—	0.00	—	0.00	—	ns
		LFE2-20	0.00	—	0.00	—	0.00	—	ns
		LFE2-35	0.00	—	0.00	—	0.00	—	ns
		LFE2-50	0.00	—	0.00	—	0.00	—	ns
		LFE2-70	0.00	—	0.00	—	0.00	—	ns
		LFE2M20	0.00	—	0.00	—	0.00	—	ns
		LFE2M35	0.00	—	0.00	—	0.00	—	ns
		LFE2M50	0.00	—	0.00	—	0.00	—	ns
		LFE2M70	0.00	—	0.00	—	0.00	—	ns
		LFE2M100	0.00	—	0.00	—	0.00	—	ns
f_{MAX_IOE}	Clock Frequency of I/O and PFU Register	ECP2/M	—	420	—	357	—	311	MHz
General I/O Pin Parameters (using Primary Clock with PLL)[1]									
t_{COPLL}[10]	Clock to Output - PIO Output Register	LFE2-6	—	2.30	—	2.60	—	2.80	ns
		LFE2-12	—	2.30	—	2.60	—	2.80	ns
		LFE2-20	—	2.30	—	2.60	—	2.80	ns
		LFE2-35	—	2.30	—	2.60	—	2.80	ns
		LFE2-50	—	2.30	—	2.60	—	2.80	ns
		LFE2-70	—	2.30	—	2.60	—	2.80	ns
		LFE2M20	—	2.30	—	2.60	—	2.80	ns
		LFE2M35	—	2.30	—	2.60	—	2.80	ns
		LFE2M50	—	2.60	—	2.90	—	3.10	ns
		LFE2M70	—	2.60	—	2.90	—	3.10	ns
		LFE2M100	—	2.70	—	3.00	—	3.20	ns
t_{SUPLL}	Clock to Data Setup - PIO Input Register	LFE2-6	0.70	—	0.80	—	0.90	—	ns
		LFE2-12	0.70	—	0.80	—	0.90	—	ns
		LFE2-20	0.70	—	0.80	—	0.90	—	ns
		LFE2-35	0.70	—	0.80	—	0.90	—	ns
		LFE2-50	0.70	—	0.80	—	0.90	—	ns
		LFE2-70	0.70	—	0.80	—	0.90	—	ns
		LFE2M20	0.70	—	0.80	—	0.90	—	ns
		LFE2M35	0.70	—	0.80	—	0.90	—	ns
		LFE2M50	0.70	—	0.80	—	0.90	—	ns
		LFE2M70	0.70	—	0.80	—	0.90	—	ns
		LFE2M100	0.80	—	0.90	—	1.00	—	ns

LatticeECP2/M sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Byte Data Flow				
t_{SUCBDI}	Byte D[0:7] Setup Time to CCLK	7	—	ns
t_{HCBDI}	Byte D[0:7] Hold Time to CCLK	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
t_{SUCS}	CSN[0:1] Setup Time to CCLK	7	—	ns
t_{HCS}	CSN[0:1] Hold Time to CCLK	1	—	ns
t_{SUWD}	Write Signal Setup Time to CCLK	7	—	ns
t_{HWD}	Write Signal Hold Time to CCLK	1	—	ns
t_{DCB}	CCLK to BUSY Delay Time	—	12	ns
t_{CORD}	CCLK to Out for Read Data	—	12	ns
sysCONFIG Byte Slave Clocking				
t_{BSCH}	Byte Slave CCLK Minimum High Pulse	6	—	ns
t_{BSCL}	Byte Slave CCLK Minimum Low Pulse	9	—	ns
t_{BSCYC}	Byte Slave CCLK Cycle Time	15	—	ns
sysCONFIG Serial (Bit) Data Flow				
t_{SUSCDI}	DI Setup Time to CCLK Slave Mode	7	—	ns
t_{HSCDI}	DI Hold Time to CCLK Slave Mode	1	—	ns
t_{CODO}	CCLK to DOUT in Flowthrough Mode	—	12	ns
sysCONFIG Serial Slave Clocking				
t_{SSCH}	Serial Slave CCLK Minimum High Pulse	6	—	ns
t_{SSCL}	Serial Slave CCLK Minimum Low Pulse	6	—	ns
sysCONFIG POR, Initialization and Wake-up				
t_{ICFG}	Minimum Vcc to INITN High	—	28	ms
t_{VMC}	Time from t_{ICFG} to Valid Master CCLK	—	2	us
t_{PRGMRJ}	PROGRAMN Pin Pulse Rejection	—	8	ns
t_{PRGM}	PROGRAMN Low Time to Start Configuration	25	—	ns
t_{DINIT}	PROGRAMN High to INITN High Delay[1]	—	1.5	ms
$t_{DPPINIT}$	Delay Time from PROGRAMN Low to INITN Low	—	37	ns
$t_{DPPDONE}$	Delay Time from PROGRAMN Low to DONE Low	—	37	ns
t_{IODISS}	User I/O Disable from PROGRAMN Low	—	35	ns
t_{IOENSS}	User I/O Enabled Time from CCLK Edge During Wake-up Sequence	—	25	ns
t_{MWC}	Additional Wake Master Clock Signals after DONE Pin High	120	—	cycles
sysCONFIG SPI Port[2]				
t_{CFGX}	INITN High to CCLK Low	—	1	µs
t_{CSSPI}	INITN High to CSSPIN Low	—	2	us
t_{CSCCLK}	CCLK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CCLK Low to Output Valid	—	15	ns
t_{SOE}	CSSPIN[0:1] Active Setup Time	300	—	ns
t_{CSPID}	CSSPIN[0:1] Low to First CCLK Edge Setup Time	300+3cyc	600+6cyc	ns

LatticeECP2M Pin Information Summary, LFE2M50, LFE2M70 and LFE2M100

Pin Type		LFE2M50			LFE2M70		LFE2M100	
		484 fpBGA	672 fpBGA	900 fpBGA	900 fpBGA	1152 fpBGA	900 fpBGA	1152 fpBGA
Single Ended User I/O		270	372	410	416	436	416	520
Differential Pair User I/O		135	185	205	208	218	207	260
Configuration	TAP Pins	5	5	5	5	5	5	5
	Muxed Pins	14	14	14	14	14	14	14
	Dedicated Pins (Non TAP)	7	7	7	7	7	7	7
Non Configuration	Muxed Pins	69	72	72	75	76	74	78
	Dedicated Pins	3	3	3	3	3	3	3
VCC		16	20	62	44	44	44	44
VCCAUX		8	26	18	16	12	16	12
VCCPLL		4	8	4	4	4	4	4
VCCIO	Bank0	4	5	6	6	7	6	7
	Bank1	3	4	6	6	7	6	7
	Bank2	4	5	9	9	9	9	9
	Bank3	4	5	9	9	9	9	9
	Bank4	4	4	6	6	7	6	7
	Bank5	4	5	6	6	7	6	7
	Bank6	4	5	9	9	9	9	9
	Bank7	4	5	9	9	9	9	9
	Bank8	2	2	2	2	2	2	2
GND, GND0 to GND7		57	80	122	122	134	122	134
NC		31	35	121	63	283	63	199
Single Ended/ Differential I/O Pairs per Bank (including emulated with resistors)	Bank0	36/18	63/31	56/28	34/17	46/23	34/17	54/27
	Bank1	18/9	18/9	36/18	42/21	34/17	42/21	44/22
	Bank2	30/15	50/25	54/27	70/35	72/36	70/35	80/40
	Bank3	36/18	43/21	44/22	60/30	64/32	60/30	80/40
	Bank4	42/21	24/12	38/19	38/19	40/20	38/19	44/22
	Bank5	28/14	60/30	58/29	40/20	40/20	40/20	46/23
	Bank6	40/20	54/27	60/30	62/31	66/33	62/31	82/41
	Bank7	40/20	60/30	64/32	70/35	74/37	70/35	90/45
	Bank8	0/0	0/0	0/0	0/0	0/0	0/0	0/0
True LVDS I/O Pairs per Bank	Bank0 (Top Edge)	0	0	0	0	0	0	0
	Bank1 (Top Edge)	0	0	0	0	0	0	0
	Bank2 (Right Edge)	7	12	13	17	18	17	20
	Bank3 (Right Edge)	9	11	11	15	16	15	20
	Bank4 (Bottom Edge)	0	0	0	0	0	0	0
	Bank5 (Bottom Edge)	0	0	0	0	0	0	0
	Bank6 (Left Edge)	10	14	15	15	16	15	20
	Bank7 (Left Edge)	10	15	17	17	18	17	22
	Bank8 (Right Edge)	0	0	0	0	0	0	0

LatticeECP2 Power Supply and NC

Signals	144 TQFP[3]	208 PQFP[3]	256 fpBGA[4]	484 fpBGA[4]
VCC	16, 22, 29, 48, 54, 83, 94, 102, 128, 135	12, 19, 28, 40, 74, 80, 97, 116, 129, 140, 146, 171, 188, 198	**LFE2-6:** G7, G9, G10, H7, J10, K10, K8 **LFE2-12/LFE2-20:** G7, G9, G10, H7, J10, K10, K8	**LFE2-12/LFE2-20:** N6, N18, J10, J11, J12, J13, K14, K9, L14, L9, M14, M9, N14, N9, P10, P11, P12, P13 **LFE2-35/LFE2-50:** J10, J11, J12, J13, K14, K9, L14, L9, M14, M9, N14, N9, P10, P11, P12, P13
VCCIO0	139	195, 206	C5, E7	G10, G9, H8, H9
VCCIO1	117	162, 170	C12, E10	G11, G12, G13, G14
VCCIO2	106	143, 148	E14, G12	H14, H15, J15, K16
VCCIO3	89	123, 135	K12, M14	L16, M16, N16, P16
VCCIO4	64	93, 100	M10, P12	R14, T12, T13, T14
VCCIO5	42	55, 63	M7, P5	R9, T10, T11, T9
VCCIO6	31	38, 44	K5, M3	N7, P7, P8, R8
VCCIO7	9	10, 14	E3, G5	J8, K7, L7, M7
VCCIO8	85	113, 118	T15	P15, R15
VCCJ	35	51	K7	T8
VCCAUX	6, 39, 90, 142	7, 30, 70, 86, 125, 151, 174, 190	G8, H10, J7, K9	G5, K5, R5, V7, V11, V8, V13, V15, M17, P17, E17, G18, D11, F13, C5, E6
VCCPLL	None	None	None	**LFE2-12/LFE2-20:** None **LFE2-35:** N6, N18 **LFE2-50:** N6, N18, K6, J16
GND[1]	11, 21, 30, 47, 51, 61, 81, 95, 105, 120, 133, 138	5, 13, 17, 25, 32, 42, 60, 68, 77, 81, 89, 102, 115, 122, 139, 145, 159, 169, 175, 184, 192, 201	A1, A16, B12, B5, C8, E15, E2, H14, H8, H9, J3, J8, J9, M15, M2, P9, R12, R5, T1, T16	A22, AA19, AA4, AB1, AB22, B19, B4, C14, C9, D2, D21, F17, F6, H10, H11, H12, H13, J14, J20, J3, J9, K10, K11, K12, K13, K15, K8, L10, L11, L12, L13, L15, L8, M10, M11, M12, M13, M15, M8, N10, N11, N12, N13, N15, N8, P14, P20, P3, P9, R10, R11, R12, R13, U17, U6, W2, W21, Y14, Y9, A1
NC[2]	**LFE2-6:** 45, 46, 124, 127 **LFE2-12:** 127	None	**LFE2-6:** K6, R3, P4 **LFE2-12/LFE2-20:** None	**LFE2-12:** E3, F3, F1, H4, F2, H5, G1, G3, G2, G4, K6, N1, M2, N2, M1, N3, N5, N4, P5, N19, M19, J22, L22, H22, K22, J16, D22, F21, E21, E22, H19, G20, G19, F20, C21, C22, H6, J6, H3, H2, H17, H16, H20, H18 **LFE2-20/LFE2-35:** K6, J16, H6, J6, H3, H2, H17, H16, H20, H18 **LFE2-50:** None

1. All grounds must be electrically connected at the board level. For fpBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
2. NC pins should not be connected to any active signals, VCC or GND.
3. Pin orientation follows the conventional order from the pin 1 marking of the top side view and counter-clockwise.
4. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 208 PQFP (Cont.)

	LFE2-12E/SE				LFE2-20E/SE			
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential
184	GND	-			GND	-		
185	PT28A	0	PCLKT0_0	T	PT37A	0	PCLKT0_0	T
186	PT26B	0		C	PT36B	0		C
187	PT26A	0		T	PT36A	0		T
188	VCC	-			VCC	-		
189	PT20B	0		C	PT30B	0		C
190	VCCAUX	-			VCCAUX	-		
191	PT20A	0		T	PT30A	0		T
192	GND	-			GND	-		
193	PT18B	0		C	PT26B	0		C
194	PT18A	0		T	PT26A	0		T
195	VCCIO0	0			VCCIO0	0		
196	PT16B	0		C	PT20B	0		C
197	PT16A	0		T	PT20A	0		T
198	VCC	-			VCC	-		
199	PT12B	0		C	PT12B	0		C
200	PT12A	0		T	PT12A	0		T
201	GND	-			GND	-		
202	PT8B	0		C	PT8B	0		C
203	PT8A	0		T	PT8A	0		T
204	PT6B	0		C	PT6B	0		C
205	PT6A	0		T	PT6A	0		T
206	VCCIO0	0			VCCIO0	0		
207	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C
208	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

	LFE2-12E/12SE				LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
C2	PT3A	0		T	PT3A	0		T
J10	VCC	-			VCC	-		
J11	VCC	-			VCC	-		
J12	VCC	-			VCC	-		
J13	VCC	-			VCC	-		
K14	VCC	-			VCC	-		
K9	VCC	-			VCC	-		
L14	VCC	-			VCC	-		
L9	VCC	-			VCC	-		
M14	VCC	-			VCC	-		
M9	VCC	-			VCC	-		
N14	VCC	-			VCC	-		
N9	VCC	-			VCC	-		
P10	VCC	-			VCC	-		
P11	VCC	-			VCC	-		
P12	VCC	-			VCC	-		
P13	VCC	-			VCC	-		
G10	VCCIO0	0			VCCIO0	0		
G9	VCCIO0	0			VCCIO0	0		
H9	VCCIO0	0			VCCIO0	0		
H8	VCCIO0	0			VCCIO0	0		
G11	VCCIO1	1			VCCIO1	1		
G12	VCCIO1	1			VCCIO1	1		
G13	VCCIO1	1			VCCIO1	1		
G14	VCCIO1	1			VCCIO1	1		
H14	VCCIO2	2			VCCIO2	2		
H15	VCCIO2	2			VCCIO2	2		
J15	VCCIO2	2			VCCIO2	2		
K16	VCCIO2	2			VCCIO2	2		
L16	VCCIO3	3			VCCIO3	3		
M16	VCCIO3	3			VCCIO3	3		
N16	VCCIO3	3			VCCIO3	3		
P16	VCCIO3	3			VCCIO3	3		
R14	VCCIO4	4			VCCIO4	4		
T12	VCCIO4	4			VCCIO4	4		
T13	VCCIO4	4			VCCIO4	4		
T14	VCCIO4	4			VCCIO4	4		
R9	VCCIO5	5			VCCIO5	5		
T10	VCCIO5	5			VCCIO5	5		
T11	VCCIO5	5			VCCIO5	5		
T9	VCCIO5	5			VCCIO5	5		
N7	VCCIO6	6			VCCIO6	6		
P7	VCCIO6	6			VCCIO6	6		
P8	VCCIO6	6			VCCIO6	6		

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

	LFE2-20E/20SE				LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N15	GND	-			GND	-		
N17	GND	-			GND	-		
P10	GND	-			GND	-		
P12	GND	-			GND	-		
P13	GND	-			GND	-		
P14	GND	-			GND	-		
P15	GND	-			GND	-		
P17	GND	-			GND	-		
R13	GND	-			GND	-		
R14	GND	-			GND	-		
T10	GND	-			GND	-		
T11	GND	-			GND	-		
T16	GND	-			GND	-		
T17	GND	-			GND	-		
T24	GND	-			GND	-		
T3	GND	-			GND	-		
U10	GND	-			GND	-		
U11	GND	-			GND	-		
U13	GND	-			GND	-		
U14	GND	-			GND	-		
U16	GND	-			GND	-		
U17	GND	-			GND	-		
V13	GND	-			GND	-		
V14	GND	-			GND	-		
V21	GND	-			GND	-		
V6	GND	-			GND	-		
M3	NC	-			NC	-		
N6	NC	-			NC	-		
P24	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
F15	NC	-			NC	-		
F14	NC	-			NC	-		
F13	NC	-			NC	-		
G12	NC	-			NC	-		
G13	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

***For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated sysCONFIG pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).

****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
P8	PL45A	6	LDQ48	T	PL49A	6	LDQ52	T
R6	PL45B	6	LDQ48	C	PL49B	6	LDQ52	C
VCCIO	VCCIO6	6			VCCIO6	6		
T1	PL46A	6	LDQ48	T (LVDS)*	PL50A	6	LDQ52	T*
U1	PL46B	6	LDQ48	C (LVDS)*	PL50B	6	LDQ52	C*
R7	PL47A	6	LDQ48	T	PL51A	6	LDQ52	T
T5	PL47B	6	LDQ48	C	PL51B	6	LDQ52	C
GNDIO	GNDIO6	-			GNDIO6	-		
U3	PL48A	6	LDQS48	T (LVDS)*	PL52A	6	LDQS52	T*
U4	PL48B	6	LDQ48	C (LVDS)*	PL52B	6	LDQ52	C*
U5	PL49A	6	LDQ48	T	PL53A	6	LDQ52	T
VCCIO	VCCIO6	6			VCCIO6	6		
U6	PL49B	6	LDQ48	C	PL53B	6	LDQ52	C
U2	PL50A	6	LDQ48	T (LVDS)*	PL54A	6	LDQ52	T*
V1	PL50B	6	LDQ48	C (LVDS)*	PL54B	6	LDQ52	C*
W2	PL51A	6	LDQ48	T	PL55A	6	LDQ52	T
GNDIO	GNDIO6	-			GNDIO6	-		
V2	PL51B	6	LDQ48	C	PL55B	6	LDQ52	C
V4	PL55A	6	LDQ57	T (LVDS)*	PL59A	6		T*
VCCIO	VCCIO6	6			VCCIO6	6		
V3	PL55B	6	LDQ57	C (LVDS)*	PL59B	6		C*
-	-	-			GNDIO6	-		
W4	PL57A	6	LLM0_GPLLT_IN_A**/LDQS57****	T (LVDS)*	PL62A	6	LLM0_GPLLT_IN_A	T*
GNDIO	GNDIO6	-			GNDIO6	-		
W3	PL57B	6	LLM0_GPLLC_IN_A**/LDQ57	C (LVDS)*	PL62B	6	LLM0_GPLLC_IN_A	C*
W1	PL58A	6	LLM0_GPLLT_FB_A/LDQ57	T	PL63A	6	LLM0_GPLLT_FB_A	T
Y1	PL58B	6	LLM0_GPLLC_FB_A/LDQ57	C	PL63B	6	LLM0_GPLLC_FB_A	C
VCCIO	VCCIO6	6			VCCIO6	6		
AA1	PL59A	6	LLM0_GDLLT_IN_A**/LDQ57	T (LVDS)*	PL64A	6	LLM0_GDLLT_IN_A	T*
AB1	PL59B	6	LLM0_GDLLC_IN_A**/LDQ57	C (LVDS)*	PL64B	6	LLM0_GDLLC_IN_A	C*
U7	PL60A	6	LLM0_GDLLT_FB_A/LDQ57	T	PL65A	6	LLM0_GDLLT_FB_A	T
V6	PL60B	6	LLM0_GDLLC_FB_A/LDQ57	C	PL65B	6	LLM0_GDLLC_FB_A	C
GNDIO	GNDIO6	-			GNDIO6	-		
T8	LLM0_PLLCAP	6			LLM0_PLLCAP	6		
W5	PL62A	6	LDQ66	T (LVDS)*	PL67A	6	LDQ71	T*
Y4	PL62B	6	LDQ66	C (LVDS)*	PL67B	6	LDQ71	C*
U8	PL63A	6	LDQ66	T	PL68A	6	LDQ71	T
W6	PL63B	6	LDQ66	C	PL68B	6	LDQ71	C
VCCIO	VCCIO6	6			VCCIO6	6		
Y3	PL64A	6	LDQ66	T (LVDS)*	PL69A	6	LDQ71	T*
AA3	PL64B	6	LDQ66	C (LVDS)*	PL69B	6	LDQ71	C*
V7	NC	-			PL70A	6	LDQ71	T
Y5	PL65B	6	LDQ66	C	PL70B	6	LDQ71	C
GNDIO	GNDIO6	-			GNDIO6	-		
AB2	PL66A	6	LDQS66	T (LVDS)*	PL71A	6	LDQS71	T*
AA4	PL66B	6	LDQ66	C (LVDS)*	PL71B	6	LDQ71	C*
Y6	PL67A	6	LDQ66	T	PL72A	6	LDQ71	T
VCCIO	VCCIO6	6			VCCIO6	6		

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AF4	PB17B	5	BDQ15	C	PB17B	5	BDQ15	C
VCCIO	VCCIO5	5			VCCIO5	5		
AF5	PB18A	5	BDQ15	T	PB18A	5	BDQ15	T
AF6	PB18B	5	BDQ15	C	PB18B	5	BDQ15	C
Y12	PB19A	5	BDQ15	T	PB19A	5	BDQ15	T
GNDIO	GNDIO5	-			GNDIO5	-		
AB11	PB19B	5	BDQ15	C	PB19B	5	BDQ15	C
-	-	-			VCCIO5	5		
-	-	-			GNDIO5	-		
AD7	PB20A	5	BDQ24	T	PB29A	5	BDQ33	T
AF7	PB20B	5	BDQ24	C	PB29B	5	BDQ33	C
AD8	PB21A	5	BDQ24	T	PB30A	5	BDQ33	T
AA12	PB21B	5	BDQ24	C	PB30B	5	BDQ33	C
AE8	PB22A	5	BDQ24	T	PB31A	5	BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AF8	PB22B	5	BDQ24	C	PB31B	5	BDQ33	C
AD9	PB23A	5	BDQ24	T	PB32A	5	BDQ33	T
AC10	PB23B	5	BDQ24	C	PB32B	5	BDQ33	C
AC11	PB24A	5	BDQS24	T	PB33A	5	BDQS33	T
GNDIO	GNDIO5	-			GNDIO5	-		
AB12	PB24B	5	BDQ24	C	PB33B	5	BDQ33	C
AD10	PB25A	5	BDQ24	T	PB34A	5	BDQ33	T
Y13	PB25B	5	BDQ24	C	PB34B	5	BDQ33	C
AF9	PB26A	5	BDQ24	T	PB35A	5	BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AE9	PB26B	5	BDQ24	C	PB35B	5	BDQ33	C
AF10	PB27A	5	BDQ24	T	PB36A	5	BDQ33	T
AE10	PB27B	5	BDQ24	C	PB36B	5	BDQ33	C
AD11	PB28A	5	BDQ24	T	PB37A	5	BDQ33	T
GNDIO	GNDIO5	-			GNDIO5	-		
AF11	PB28B	5	BDQ24	C	PB37B	5	BDQ33	C
VCCIO	VCCIO5	5			VCCIO5	5		
GNDIO	GNDIO5	-			GNDIO5	-		
AA13	PB33A	5	BDQS33****	T	PB42A	5	BDQS42****	T
AB13	PB33B	5	BDQ33	C	PB42B	5	BDQ42	C
W14	PB34A	5	VREF2_5/BDQ33	T	PB43A	5	VREF2_5/BDQ42	T
AC12	PB34B	5	VREF1_5/BDQ33	C	PB43B	5	VREF1_5/BDQ42	C
AF12	PB35A	5	PCLKT5_0/BDQ33	T	PB44A	5	PCLKT5_0/BDQ42	T
AD12	PB35B	5	PCLKC5_0/BDQ33	C	PB44B	5	PCLKC5_0/BDQ42	C
VCCIO	VCCIO5	5			VCCIO5	5		
GNDIO	GNDIO5	-			GNDIO5	-		
AC13	PB40A	4	PCLKT4_0/BDQ42	T	PB49A	4	PCLKT4_0/BDQ51	T
VCCIO	VCCIO4	4			VCCIO4	4		
Y14	PB40B	4	PCLKC4_0/BDQ42	C	PB49B	4	PCLKC4_0/BDQ51	C
AB20	PB57A	4	BDQ60	T	PB50A	4	VREF2_4/BDQ51	T
AC14	PB41B	4	VREF1_4/BDQ42	C	PB50B	4	VREF1_4/BDQ51	C
AB14	PB42A	4	BDQS42****	T	PB51A	4	BDQS51****	T
GNDIO	GNDIO4	-			GNDIO4	-		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
K13	VCCIO0	0			VCCIO0	0		
D17	VCCIO1	1			VCCIO1	1		
E22	VCCIO1	1			VCCIO1	1		
E25	VCCIO1	1			VCCIO1	1		
F19	VCCIO1	1			VCCIO1	1		
K18	VCCIO1	1			VCCIO1	1		
K19	VCCIO1	1			VCCIO1	1		
F28	VCCIO2	2			VCCIO2	2		
J25	VCCIO2	2			VCCIO2	2		
K28	VCCIO2	2			VCCIO2	2		
M21	VCCIO2	2			VCCIO2	2		
M24	VCCIO2	2			VCCIO2	2		
N21	VCCIO2	2			VCCIO2	2		
N28	VCCIO2	2			VCCIO2	2		
P21	VCCIO2	2			VCCIO2	2		
R25	VCCIO2	2			VCCIO2	2		
AA28	VCCIO3	3			VCCIO3	3		
AB25	VCCIO3	3			VCCIO3	3		
AE28	VCCIO3	3			VCCIO3	3		
T25	VCCIO3	3			VCCIO3	3		
U21	VCCIO3	3			VCCIO3	3		
V21	VCCIO3	3			VCCIO3	3		
V28	VCCIO3	3			VCCIO3	3		
W21	VCCIO3	3			VCCIO3	3		
W24	VCCIO3	3			VCCIO3	3		
AA18	VCCIO4	4			VCCIO4	4		
AA19	VCCIO4	4			VCCIO4	4		
AE19	VCCIO4	4			VCCIO4	4		
AF22	VCCIO4	4			VCCIO4	4		
AG17	VCCIO4	4			VCCIO4	4		
AG25	VCCIO4	4			VCCIO4	4		
AA12	VCCIO5	5			VCCIO5	5		
AA13	VCCIO5	5			VCCIO5	5		
AE12	VCCIO5	5			VCCIO5	5		
AF9	VCCIO5	5			VCCIO5	5		
AG14	VCCIO5	5			VCCIO5	5		
AG6	VCCIO5	5			VCCIO5	5		
AA3	VCCIO6	6			VCCIO6	6		
AB6	VCCIO6	6			VCCIO6	6		
AE3	VCCIO6	6			VCCIO6	6		
T6	VCCIO6	6			VCCIO6	6		
U10	VCCIO6	6			VCCIO6	6		
V10	VCCIO6	6			VCCIO6	6		
V3	VCCIO6	6			VCCIO6	6		
W10	VCCIO6	6			VCCIO6	6		
W7	VCCIO6	6			VCCIO6	6		
F3	VCCIO7	7			VCCIO7	7		
J6	VCCIO7	7			VCCIO7	7		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
VCCIO	VCCIO3	3		
T22	PR69A	3	RDQ72	T
T29	PR68B	3	RDQ72	C (LVDS)*
T28	PR68A	3	RDQ72	T (LVDS)*
R23	PR66B	3	RLM4_SPLLC_FB_A/RDQ63	C
GNDIO	GNDIO3	-		
-	-	-		
R22	PR66A	3	RLM4_SPLLT_FB_A/RDQ63	T
P30	PR65B	3	RLM4_SPLLC_IN_A/RDQ63	C (LVDS)*
R29	PR65A	3	RLM4_SPLLT_IN_A/RDQ63	T (LVDS)*
T27	PR64B	3	RDQ63	C
VCCIO	VCCIO3	3		
T26	PR64A	3	RDQ63	T
GNDIO	GNDIO3	-		
N30	PR61B	3	RDQ63	C (LVDS)*
N29	PR61A	3	RDQ63	T (LVDS)*
VCCIO	VCCIO3	3		
R27	PR60B	3	VREF2_3/RDQ63	C
R28	PR60A	3	VREF1_3/RDQ63	T
P29	PR59B	3	PCLKC3_0/RDQ63	C (LVDS)*
P28	PR59A	3	PCLKT3_0/RDQ63	T (LVDS)*
M30	PR57B	2	PCLKC2_0/RDQ54	C
M29	PR57A	2	PCLKT2_0/RDQ54	T
GNDIO	GNDIO2	-		
P23	PR56B	2	RDQ54	C (LVDS)*
P24	PR56A	2	RDQ54	T (LVDS)*
R26	PR55B	2	RDQ54	C
P27	PR55A	2	RDQ54	T
VCCIO	VCCIO2	2		
P25	PR54B	2	RDQ54	C (LVDS)*
P26	PR54A	2	RDQS54	T (LVDS)*
K30	PR53B	2	RDQ54	C
GNDIO	GNDIO2	-		
K29	PR53A	2	RDQ54	T
N22	PR52B	2	RDQ54	C (LVDS)*
P22	PR52A	2	RDQ54	T (LVDS)*
J30	PR51B	2	RUM3_SPLLC_FB_A/RDQ54	C
VCCIO	VCCIO2	2		
J29	PR51A	2	RUM3_SPLLT_FB_A/RDQ54	T
N24	PR50B	2	RUM3_SPLLC_IN_A/RDQ54	C (LVDS)*
N23	PR50A	2	RUM3_SPLLT_IN_A/RDQ54	T (LVDS)*
N25	PR48B	2	RDQ45	C
N26	PR48A	2	RDQ45	T

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
M10	VCCIO7	7		
M7	VCCIO7	7		
N10	VCCIO7	7		
N3	VCCIO7	7		
P10	VCCIO7	7		
R6	VCCIO7	7		
AA25	VCCIO8	8		
AD28	VCCIO8	8		
AA10	VCCAUX	-		
AA11	VCCAUX	-		
AA20	VCCAUX	-		
AA21	VCCAUX	-		
K10	VCCAUX	-		
K11	VCCAUX	-		
K20	VCCAUX	-		
K21	VCCAUX	-		
L10	VCCAUX	-		
L11	VCCAUX	-		
L20	VCCAUX	-		
L21	VCCAUX	-		
Y10	VCCAUX	-		
Y11	VCCAUX	-		
Y20	VCCAUX	-		
Y21	VCCAUX	-		
A1	GND	-		
A13	GND	-		
A18	GND	-		
A24	GND	-		
A30	GND	-		
A7	GND	-		
AA14	GND	-		
AA15	GND	-		
AA16	GND	-		
AA17	GND	-		
AA24	GND	-		
AA27	GND	-		
AA4	GND	-		
AB24	GND	-		
AB7	GND	-		
AD12	GND	-		
AD19	GND	-		
AD27	GND	-		
AE22	GND	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE					LFE2M100E/SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AF1	PL78B	6	LDQ82	C (LVDS)*	PL95B	6	LDQ99	C (LVDS)*
AE5	PL79A	6	LDQ82	T	PL96A	6	LDQ99	T
AE6	PL79B	6	LDQ82	C	PL96B	6	LDQ99	C
AF4	PL80A	6	LDQ82	T (LVDS)*	PL97A	6	LDQ99	T (LVDS)*
VCCIO	VCCIO6	6			VCCIO6	6		
AF3	PL80B	6	LDQ82	C (LVDS)*	PL97B	6	LDQ99	C (LVDS)*
AF5	PL81A	6	LDQ82	T	PL98A	6	LDQ99	T
AF6	PL81B	6	LDQ82	C	PL98B	6	LDQ99	C
AG1	PL82A	6	LLM0_GPLLT_IN_A**/LDQS82	T (LVDS)*	PL99A	6	LLM0_GPLLT_IN_A**/LDQS99	T (LVDS)*
GNDIO	GNDIO6	-			GNDIO6	-		
AG2	PL82B	6	LLM0_GPLLC_IN_A**/LDQ82	C (LVDS)*	PL99B	6	LLM0_GPLLC_IN_A**/LDQ99	C (LVDS)*
AE9	PL83A	6	LLM0_GPLLT_FB_A/LDQ82	T	PL100A	6	LLM0_GPLLT_FB_A/LDQ99	T
AF7	PL83B	6	LLM0_GPLLC_FB_A/LDQ82	C	PL100B	6	LLM0_GPLLC_FB_A/LDQ99	C
VCCIO	VCCIO6	6			VCCIO6	6		
AH1	PL84A	6	LLM0_GDLLT_IN_A**/LDQ82	T (LVDS)*	PL101A	6	LLM0_GDLLT_IN_A**/LDQ99	T (LVDS)*
AH2	PL84B	6	LLM0_GDLLC_IN_A**/LDQ82	C (LVDS)*	PL101B	6	LLM0_GDLLC_IN_A**/LDQ99	C (LVDS)*
AG5	PL85A	6	LLM0_GDLLT_FB_A/LDQ82	T	PL102A	6	LLM0_GDLLT_FB_A/LDQ99	T
AG4	PL85B	6	LLM0_GDLLC_FB_A/LDQ82	C	PL102B	6	LLM0_GDLLC_FB_A/LDQ99	C
GNDIO	GNDIO6	-			GNDIO6	-		
AG6	LLM0_PLLCAP	6			LLM0_PLLCAP	6		
AJ1	PL87A	6		T	PL104A	6		T
AJ2	PL87B	6		C	PL104B	6		C
AK2	TCK	-			TCK	-		
AK1	TDI	-			TDI	-		
AL1	TMS	-			TMS	-		
AF10	TDO	-			TDO	-		
AK3	VCCJ	-			VCCJ	-		
AN2	LLC_SQ_VCCRX3	14			LLC_SQ_VCCRX3	14		
AM2	LLC_SQ_HDINP3	14		T	LLC_SQ_HDINP3	14		T
AN1	LLC_SQ_VCCIB3	14			LLC_SQ_VCCIB3	14		
AM3	LLC_SQ_HDINN3	14		C	LLC_SQ_HDINN3	14		C
AN3	LLC_SQ_VCCTX3	14			LLC_SQ_VCCTX3	14		
AP2	LLC_SQ_HDOUTP3	14		T	LLC_SQ_HDOUTP3	14		T
AM1	LLC_SQ_VCCOB3	14			LLC_SQ_VCCOB3	14		
AP3	LLC_SQ_HDOUTN3	14		C	LLC_SQ_HDOUTN3	14		C
AN4	LLC_SQ_VCCTX2	14			LLC_SQ_VCCTX2	14		
AP4	LLC_SQ_HDOUTN2	14		C	LLC_SQ_HDOUTN2	14		C
AL3	LLC_SQ_VCCOB2	14			LLC_SQ_VCCOB2	14		
AP5	LLC_SQ_HDOUTP2	14		T	LLC_SQ_HDOUTP2	14		T
AN5	LLC_SQ_VCCRX2	14			LLC_SQ_VCCRX2	14		
AM4	LLC_SQ_HDINN2	14		C	LLC_SQ_HDINN2	14		C
AL4	LLC_SQ_VCCIB2	14			LLC_SQ_VCCIB2	14		
AM5	LLC_SQ_HDINP2	14		T	LLC_SQ_HDINP2	14		T
AL6	LLC_SQ_VCCP	14			LLC_SQ_VCCP	14		
AL5	LLC_SQ_REFCLKP	14		T	LLC_SQ_REFCLKP	14		T
AK5	LLC_SQ_REFCLKN	14		C	LLC_SQ_REFCLKN	14		C
AK6	LLC_SQ_VCCAUX33	14			LLC_SQ_VCCAUX33	14		
AM6	LLC_SQ_HDINP1	14		T	LLC_SQ_HDINP1	14		T

LatticeECP2/M Family Data Sheet Supplemental Information

July 2012 **Data Sheet DS1006**

For Further Information

A variety of technical notes for the LatticeECP2/M family are available on the Lattice web site at www.latticesemi.com.

- TN1102, LatticeECP2/M sysIO Usage Guide
- TN1103, LatticeECP2/M sysCLOCK PLL Design and Usage Guide
- TN1104, LatticeECP2/M Memory Usage Guide
- TN1105, LatticeECP2/M High-Speed I/O Interface
- TN1106, Power Estimation and Management for LatticeECP2/M Devices
- TN1107, LatticeECP2/M sysDSP Usage Guide
- TN1108, LatticeECP2/M sysCONFIG Usage Guide
- TN1109, LatticeECP2/M Configuration Encryption Usage Guide
- TN1113, LatticeECP2/M Soft Error Detection (SED) Usage Guide
- TN1124, LatticeECP2M SERDES/PCS Usage Guide
- TN1162, LatticeECP2/M Hardware Checklist

For further information about interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: www.pcisig.com

LatticeECP2/M Family Data Sheet Revision History

September 2013 **Data Sheet DS1006**

Date	Version	Section	Change Summary
February 2006	01.0	—	Initial release.
August 2006	01.1	Introduction	
			Updated Table 1-1 “LatticeECP2 Family Selection Guide”.
		Architecture	Updated Figure 2-2 “PFU Diagram”.
			Updated Figure 2-13 “Secondary Clock Regions ECP2-50”.
			Updated Figure 2-25 “PIC Diagram”.
			Updated Figure 2-26 “Input Register Block for Left, Right and Bottom Edges”.
			Updated Figure 2-28 “Output Register Block for Left, Right and Bottom Edges”.
			Updated Figure 2-30 “DQS Input Routing for Left and Right Edges”.
			Updated Figure 2-32 “Edge Clock, DLL Calibration and DQS Local Bus Distribution”.
			Table 2-15 Selectable Master Clock (CCLK) Frequencies - Removed frequencies 15, 20, 21, 22, 23, 30, 34, 41, 45, 51, 55, 60.
			Replaced “CLKINDEL” with “CLKO”.
			Updated SED section.
			Qualified device migration capability when using DQS banks for DDR interfaces.
		DC and Switching Characteristics	Added VCCPLL to the Recommended Operating Conditions table.
			Removed note 5 from “Hot Specifications” section.
			Added notes 7 and 8 to “Initialization Supply” Current table.
			Change note 6 - “...down to 95MHz” to “...down to 95MHz for DDR and 133MHz for DDR2” .
			New “Typical Building Block Function Performance” numbers.
			New External Switching Characteristics numbers.
			New Internal Switching Characteristics numbers.
			New Family Timing Adders numbers.
			Updated Timings for GPLLs, SPLLs and DLLs.
			Added sysCONFIG waveforms.
			Remove HSTL15D_II from sysIO Recommended Operating Conditions table.
			Updated Supply and Initialization Currents for ECP2-50.
		Pinout Information	Added VCCPLL to the Signal Descriptions table.
			Updated Logic Signal Connections tables to include 484-fpBGA for the ECP2-50.
			Added Logic Signal Connections tables for ECP2-12 devices.
			Updated Pin Information Summary table to include ECP2-12.
			Updated Power Supply and NC Connections table to include ECP2-12.
			Added note 2 to DDR Strobe (DQS) Pin table.
			Added Information on: PCI, DDR & SPI4.2 Capabilities of the device-Package combination.